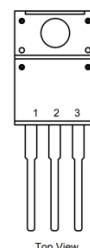
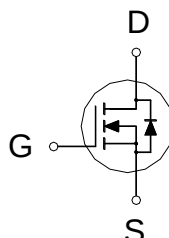




PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
250V	265m Ω	16A



Top View



Side View

1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	250	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25\text{ }^{\circ}\text{C}$	I_D	16	A
	$T_C = 100\text{ }^{\circ}\text{C}$		10	
Pulsed Drain Current ¹		I_{DM}	30	
Avalanche Current		I_{AS}	7.3	
Avalanche Energy	$L = 1\text{mH}$	E_{AS}	27	mJ
Power Dissipation	$T_C = 25\text{ }^{\circ}\text{C}$	P_D	35	W
	$T_C = 100\text{ }^{\circ}\text{C}$		14	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		3.6	$^{\circ}\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	$^{\circ}\text{C} / \text{W}$

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

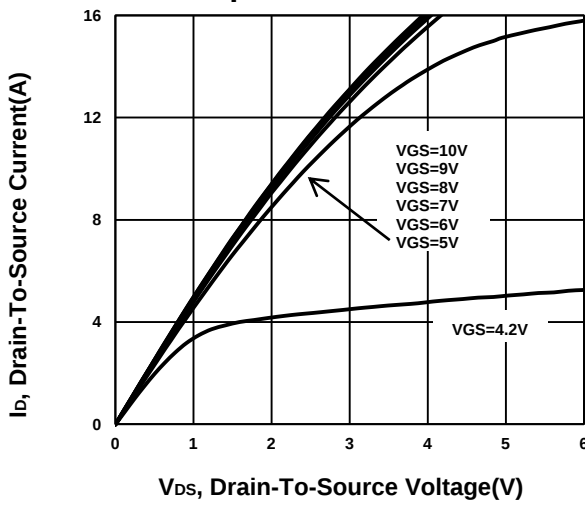
ELECTRICAL CHARACTERISTICS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	250			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2	2.8	4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA

Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 250V, V _{GS} = 0V			1	μA
		V _{DS} = 250V, V _{GS} = 0V, T _J = 55 °C			10	
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = 10V, I _D = 8A		205	265	mΩ
Forward Transconductance ¹	g _{fs}	V _{DS} = 10V, I _D = 8A		13		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 125V, f = 1MHz		734		pF
Output Capacitance	C _{oss}			63		
Reverse Transfer Capacitance	C _{rss}			14		
Gate Resistance	R _g	V _{GS} = 0V, V _{DS} = 0V ,f = 1MHz		6		Ω
Total Gate Charge ²	Q _g	V _{DS} = 125V, V _{GS} = 10V, I _D = 8A		20		nC
Gate-Source Charge ²	Q _{gs}			4.1		
Gate-Drain Charge ²	Q _{gd}			6.6		
Turn-On Delay Time ²	t _{d(on)}	V _{DD} = 125V I _D ≅ 8A, V _{GS} = 10V, R _{GEN} = 6 Ω		22		nS
Rise Time ²	t _r			33		
Turn-Off Delay Time ²	t _{d(off)}			136		
Fall Time ²	t _f			53		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _J = 25 °C)						
Continuous Current	I _S				16	A
Forward Voltage ¹	V _{SD}	I _F = 16A,V _{GS} = 0V			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 8A, dI _F /dt = 100A / μS		127		nS
Reverse Recovery Charge	Q _{rr}			588		nC

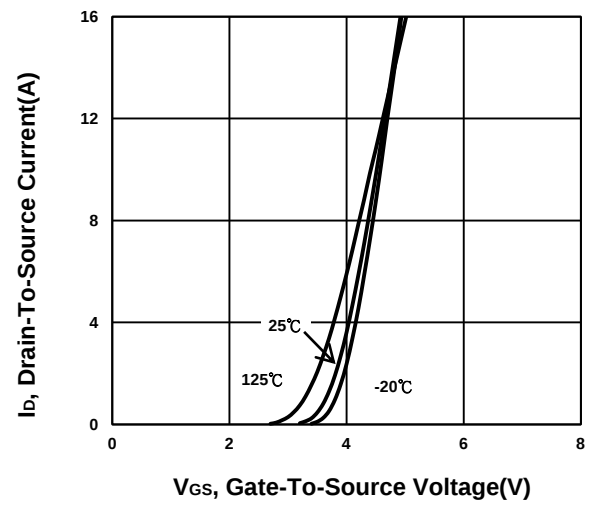
¹Pulse test : Pulse Width $\leq 300\text{ }\mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

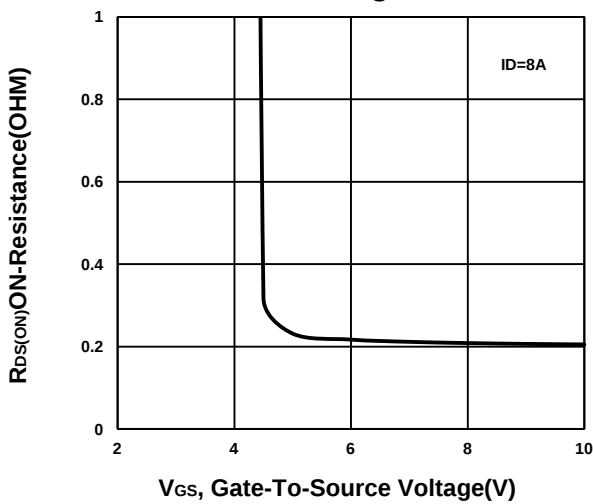
Output Characteristics



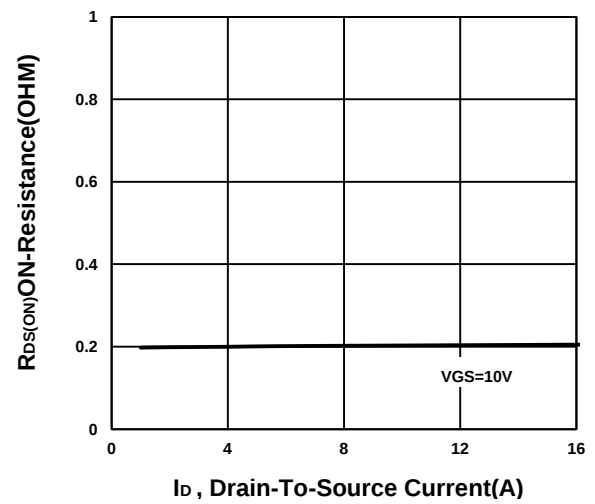
Transfer Characteristics



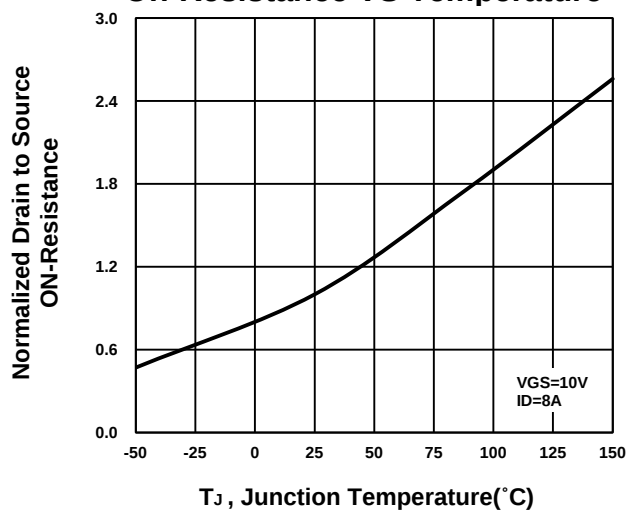
On-Resistance VS Gate-To-Source Voltage



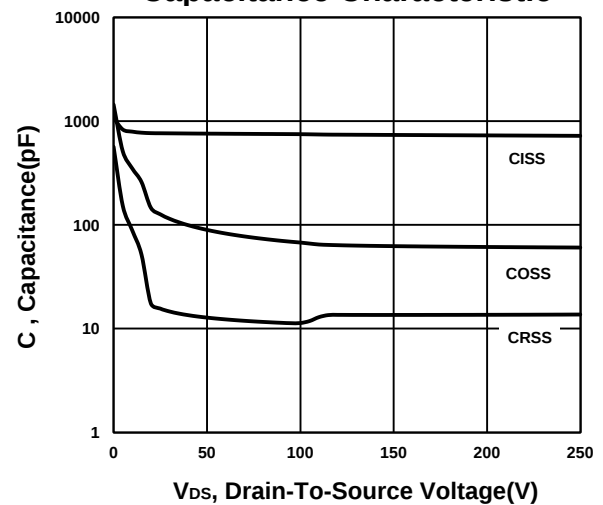
On-Resistance VS Drain Current



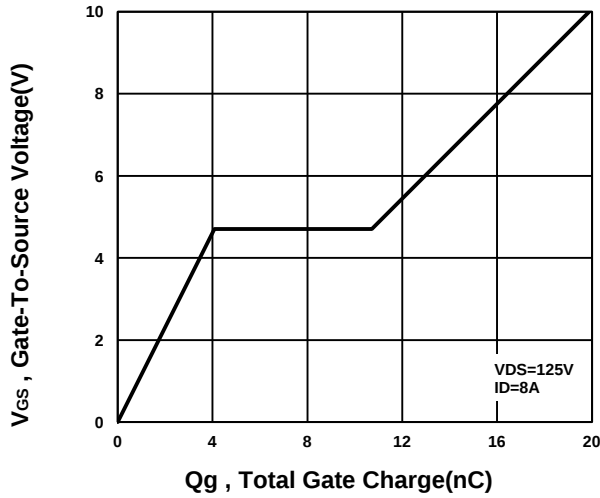
On-Resistance VS Temperature



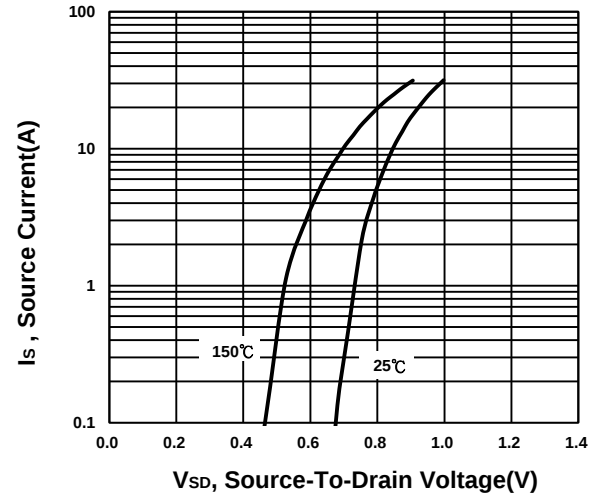
Capacitance Characteristic



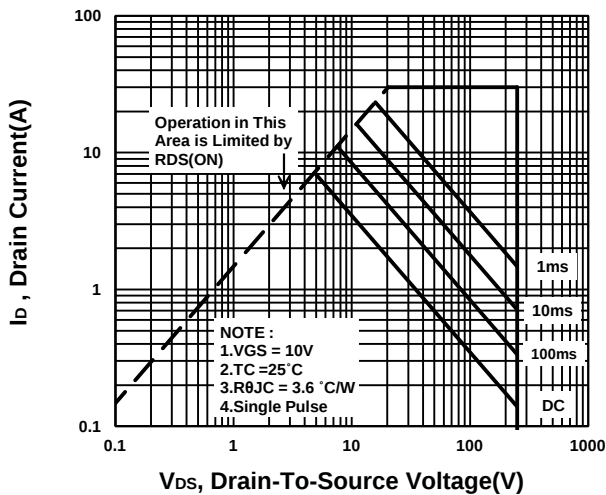
Gate charge Characteristics



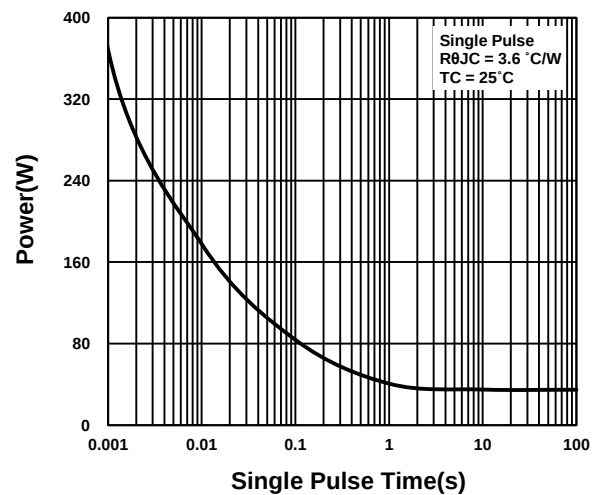
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

